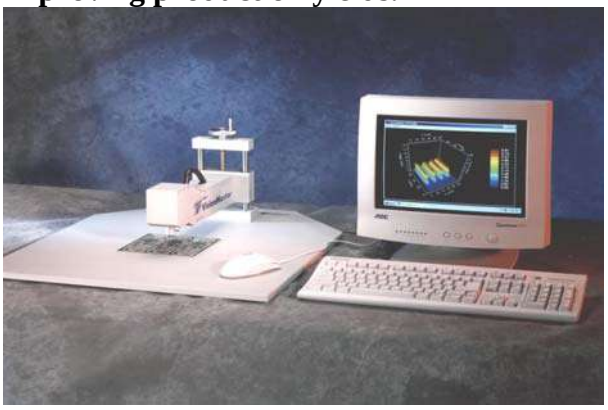
VisionMaster 150

The VisionMaster 150 system is sophisticated, 3-dimensional technology coupled with an intuitive Windows® XP interface and packaged in a rugged, bench-top system designed for the electronics production floor. With only a few minutes of training, an operator can perform accurate 3D measurements of solder paste pads, BGA's and many other PCB features. The completely automatic measurement process eliminates operator errors and offers excellent measurement repeatability. This makes the VisionMaster an exceptional value for the electronics manufacturer concerned with improving production yields.



VisionMaster 150

System Features

- Windows® XP user interface
- Full color 3-D profiles of measured features
- Accurate & repeatable measurements regardless of substrate color and reflectivity
- Automatic calculation of height, area and volume measurements
- One-year, end-user warranty including technical support.

System Includes

- Anti-static work surface
- 2.5+ GHz CPU and SVGA monitor
- Fiber optic light source
- Hardware/software reference manuals

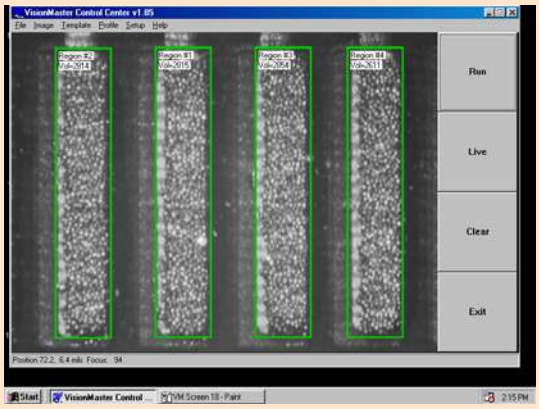
Options

- Siemens® SPC Software (LAN Ready)
- NIST Traceable Standard
- Extended Warranty

SPC Software (Optional)

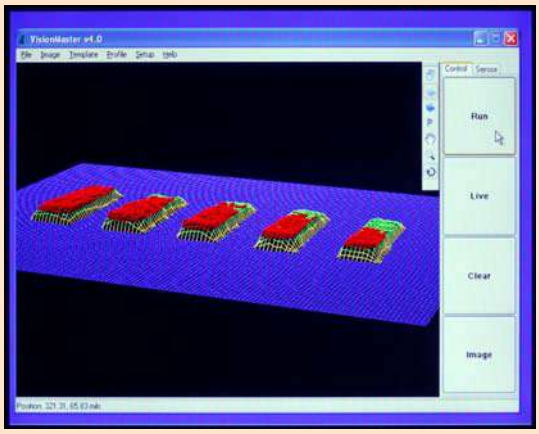
The optional Siemens® Criterion SPC software is a powerful tool that helps operators control the critical stencil printing process. Data collected by the VM150 is instantly charted by the Criterion Software. Calculations crucial to understanding printing performance are reported, including:

- X and Moving Range
- X-Bar and Sigma
- X-Bar and Range
- Histograms
- P Chart, np chart, c chart and u chart
- Pareto, weighted pareto for defects and corrective actions
- Variance and standard deviation
- Skewness, kurtosis and chi-squared for goodness of fit
- Min., max. and median values
- Cr, Cp, Cpk and lower Z values



Automated Measurements

To obtain measurements on the VM150, position the circuit board under the system's sensor to the desired location. Use manual, semi-automatic or full automatic mode to measure one of seven solder paste characteristics.



3D Color Profile Analysis

The VM150 allows operators to obtain 3D color profiles for fast and accurate paste analysis. Operators may use these profiles to help them determine what corrections are needed in their solder paste printing process, thereby reducing down time.

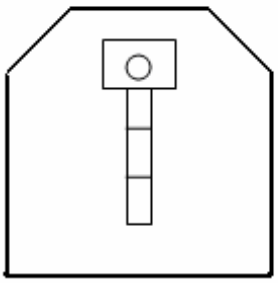
System Specifications

- **Maximum Object Thickness** 5.1 cm (2.0")
- **Standard work Surface (L*W)** 56 cm x 61 cm (22" x 24")
- **Throat depth** (sensor to support) 24 cm (9.5")
- **System Computer** 2.5+GHz – 512 MB RAM
- **Electrical Requirements** 100-240 VAC, 50-60 Hz, 2 Amps
- **Ambient Operating Temperature** 15° - 28° C (60° - 82° F)
- **Ambient Operating Humidity** <90% non-condensing
- **System Weight*** (crated) 45 Kg (99 lbs)
- **System Weight*** (un-crated) 20 Kg (44 lbs)

*not including system pc and monitor

Sensor Specifications

- **Measurement Range** 365 µm (14.4 mils)
- **Resolution** 1.78 µm (0.07mil)
- **Integral Video Camera** Solid State Video Camera
- **Field of View (FOV)** 2.1 mm x 2.8 mm (83 mils x 110 mils)
- **Illumination** Halogen-based white light



- Length: 61 cm (24.0")
- Width: 56 cm (22.0")
- Height: 24 cm (9.5")

CE

For More Information:

ASC International
1799 County Road 90, Suite 9
Maple Plain, MN 55359 U.S.A.

- Tel: USA 763-479-6210
- Fax: USA 763-478-6206
- E-mail: info@ascinternational.com
- Web: www.ascinternational.com
- Toll Free: 1-888-478-2912 (USA Only)